

TC1108

300mA CMOS LDO

Features

- Extremely Low Supply Current (50µA, Typ.)
- · Very Low Dropout Voltage
- 300mA Output Current
- High Output Voltage Accuracy
- · Standard or Custom Output Voltages
- · Over Current and Over Temperature Protection

Applications

- Battery Operated Systems
- · Portable Computers
- · Medical Instruments
- Instrumentation
- Cellular/GSM/PHS Phones
- · Linear Post-Regulators for SMPS
- Pagers

Device Selection Table

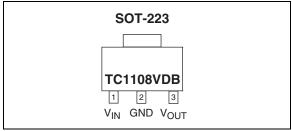
Part Number	Package	Junction Temp. Range	
TC1108-xxVDB	3-Pin SOT-223	-40°C to +125°C	

NOTE: xx indicates output voltages

Available Output Voltages: 2.5, 2.8, 3.0, 3.3, 5.0.

Other output voltages are available. Please contact Microchip Technology Inc. for details.

Package Type



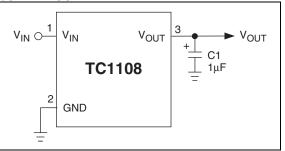
General Description

The TC1108 is a fixed output, high accuracy (typically $\pm 0.5\%$) CMOS low dropout regulator. Total supply current is typically 50μ A at full load (20 to 60 times lower than in bipolar regulators).

TC1108 key features include ultra low noise operation, very low dropout voltage (typically 240mV at full load), and fast response to step changes in load.

The TC1108 incorporates both over temperature and over current protection. The TC1108 is stable with an output capacitor of only 1μ F and has a maximum output current of 300mA. It is available in a SOT-223 package.

Typical Application



 $\Delta V_{OUT} / \Delta T$

 $\Delta V_{OUT} / \Delta V_{IN}$

ΔV_{OUT}/V_{OUT}

VIN-VOUT

IDD

eN

PSRR

I_{OUTsc} ΔV_{OUT}/ΔP_D

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Input Voltage6.5V
Output Voltage $(V_{SS} - 0.3V)$ to $(V_{IN} + 0.3V)$
Power DissipationInternally Limited (Note 6)
Maximum Voltage on Any Pin $\hdots V_{IN}$ +0.3V to -0.3V
Operating Temperature Range40°C < T_J < 125°C
Storage Temperature65°C to +150°C

V_{OUT} Temperature Coefficient

Power Supply Rejection Ratio

Output Short Circuit Current

Line Regulation

Load Regulation

Dropout Voltage

Supply Current

Output Noise

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

ppm/°C

%

%

mV

μΑ

dB

mΑ

V/W

nV/√Hz

0.35

2.0

30

160

480

90

650

Note 2

 $I_L = 0.1 \text{mA}$

 $I_{L} = 100 mA$

 $F_{RE} \le 1 kHz$

 $V_{OUT} = 0V$

 $R_{LOAD} = 50\Omega$

Note 5

 $(V_R + 1V) \le V_{IN} \le 6V$

I_L = 300mA (Note 4)

 $F = 10kHz, C_{OUT} = 1\mu F,$

I_L = 0.1mA to I_{OUTMAX} (Note 3)

TC1108 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $V_{IN} = V_{OUT} + 1V$, $I_L = 100\mu$ A, $C_L = 3.3\mu$ F, $T_A = 25^{\circ}$ C, unless otherwise noted. Boldface type specifications apply for junction temperatures of -40°C to +125°C.						
Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
V _{IN}	Input Operating Voltage	2.7	_	6.0	V	Note 7
I _{OUTMAX}	Maximum Output Current	300	—	—	mA	
V _{OUT}	Output Voltage	 V _R – 2.5%	V _R ±0.5%	 V _R + 2.5%	V	Note 1

40

0.05

0.5

20

80

240

50

60

550

0.04

260

Note 1: V_R is the regulator output voltage setting.

Thermal Regulation

2: TC $V_{OUT} = (V_{OUTMAX} - V_{OUTMIN}) \times 10^6$

V_{OUT} x ΔT

3: Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.

4: Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at a 1V differential.

5: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at V_{IN} = 6V for T = 10 msec.

6: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Section 4.0 Thermal Considerations for more details.

7: The minimum V_{IN} has to justify the conditions: $V_{IN} \ge V_R + V_{DROPOUT}$ and $V_{IN} \ge 2.7V$ for I_L = 0.1mA to I_{OUTMAX}.

_

_

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

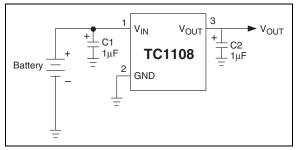
Pin No. (3-Pin SOT-223)	Symbol	Description	
1	V _{IN}	Unregulated supply input.	
2	GND	Ground terminal.	
3	V _{OUT}	Regulated voltage output.	

3.0 DETAILED DESCRIPTION

The TC1108 is a precision, fixed output LDO. Unlike bipolar regulators, the TC1108's supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation over the entire 0mA to I_{OUTMAX} operating load current range, (an important consideration in RTC and CMOS RAM battery back-up applications).

Figure 3-1 shows a typical application circuit.

FIGURE 3-1: TYPICAL APPLICATION CIRCUIT



3.1 Output Capacitor

A 1 μ F (min) capacitor from V_{OUT} to ground is required. The output capacitor should have an effective series resistance greater than 0.1 Ω and less than 5.0 Ω . A 1 μ F capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalums are recommended for applications operating below -25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

4.0 THERMAL CONSIDERATIONS

4.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 150°C. The regulator remains off until the die temperature drops to approximately 140°C.

4.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst case actual power dissipation:

EQUATION 4-1:

$$\begin{split} P_D &\approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX} \\ \\ Where: \\ P_D &= Worst \ case \ actual \ power \ dissipation \\ V_{INMAX} &= Maximum \ voltage \ on \ V_{IN} \\ V_{OUTMIN} &= Minimum \ regulator \ output \ voltage \\ I_{LOADMAX} &= Maximum \ output \ (load) \ current \end{split}$$

The maximum allowable power dissipation (Equation 4-2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (T_{JMAX}) and the thermal resistance from junction-to-air (θ_{JA}).

EQUATION 4-2:

$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$

Where all terms are previously defined.

Table 4-1 shows various values of θ_{JA} for the TC1108 versus board copper area.

TABLE 4-1: THERMAL RESISTANCE GUIDELINES FOR TC1108

Copper Area (Topside)*	Copper Area (Backside)	Board Area	Thermal Resistance (θ _{JA})
2500 sq mm	2500 sq mm	2500 sq mm	45°C/W
1000 sq mm	2500 sq mm	2500 sq mm	45°C/W
225 sq mm	2500 sq mm	2500 sq mm	53°C/W
100 sq mm	2500 sq mm	2500 sq mm	59°C/W
1000 sq mm	1000 sq mm	1000 sq mm	52°C/W
1000 sq mm	0 sq mm	1000 sq mm	55°C/W

NOTE: *Tab of device attached to topside copper

Equation 4-1 can be used in conjunction with Equation 4-2 to ensure regulator thermal operation is within limits. For example:

Given:

$$\begin{array}{ll} V_{INMAX} &= 3.3V + 10\% \\ V_{OUTMIN} &= 2.7V - 0.5\% \\ I_{LOADMAX} &= 275mA \\ T_{JMAX} &= 125^{\circ}C \\ T_{AMAX} &= 95^{\circ}C \\ \theta_{JA} &= 59^{\circ}C/W \end{array}$$

Find: 1. Actual power dissipation 2. Maximum allowable dissipation

Actual power dissipation:

$$\mathsf{P}_{\mathsf{D}}\approx(\mathsf{V}_{\mathsf{INMAX}}-\mathsf{V}_{\mathsf{OUTMIN}})\mathsf{I}_{\mathsf{LOADMAX}}$$

$$= [(3.3 \times 1.1) - (2.7 \times .995)]275 \times 10^{-3}$$

= 260mW

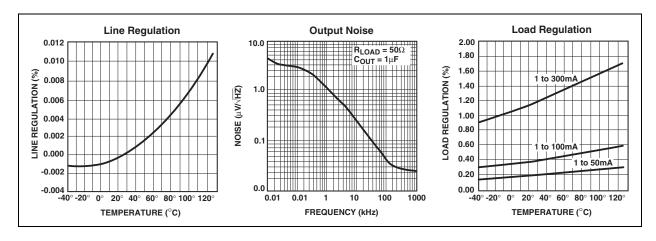
Maximum allowable power dissipation:

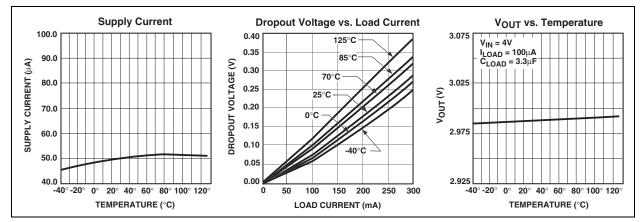
$$P_{DMAX} = \frac{(T_{JMAX} - T_{AMAX})}{\theta_{JA}}$$
$$= \frac{(125 - 95)}{59}$$
$$= 508 \text{mW}$$

In this example, the TC1108 dissipates a maximum of 260mW; below the allowable limit of 508mW. In a similar manner, Equation 4-1 and Equation 4-2 can be used to calculate maximum current and/or input voltage limits. For example, the maximum allowable V_{IN} , is found by sustituting the maximum allowable power dissipation of 508mW into Equation 4-1, from which $V_{INMAX} = 4.6V$.

5.0 TYPICAL CHARACTERISTICS

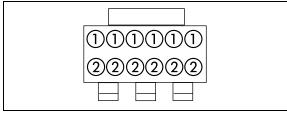
Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.





6.0 PACKAGING INFORMATION

6.1 Package Marking Information

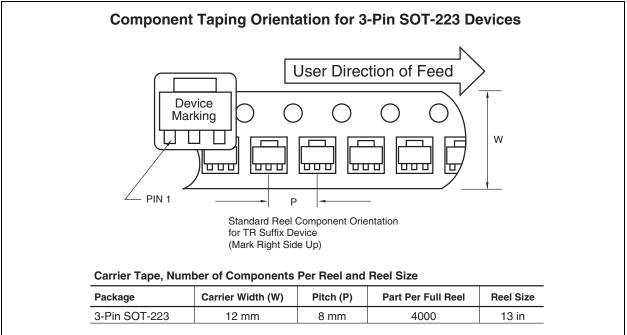


"1" = part number code

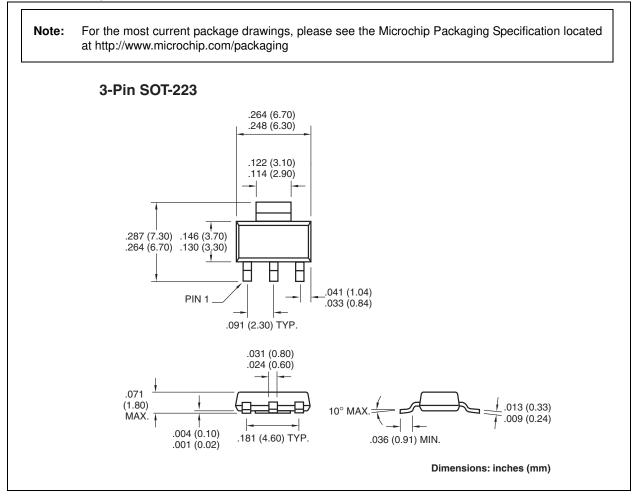
"2" = represents temperature + date code + lot identity + subcontractor identity

TC1108 (V)	Code
TC1108-2.5VDB	110825
TC1108-2.8VDB	110828
TC1108-3.0VDB	110830
TC1108-3.3VDB	110833
TC1108-5.0VDB	110850

6.2 Taping Form



6.3 Package Dimensions



REVISION HISTORY

Revision C (November 2012)

Added a note to the package outline drawing.

SALES AND SUPPORT

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- 1. Your local Microchip sales office
- 2. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

TC1108

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. & KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2002-2012, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Rinted on recycled paper.

ISBN: 9781620767351

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and water fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and mulfacture of development systems is ISO 9001:2000 certified.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://www.microchip.com/ support

Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Cleveland Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Indianapolis Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto Mississauga, Ontario, Canada Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong Tel: 852-2401-1200 Fax: 852-2401-3431 Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hangzhou Tel: 86-571-2819-3187 Fax: 86-571-2819-3189

China - Hong Kong SAR Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Osaka Tel: 81-66-152-7160 Fax: 81-66-152-9310

Japan - Yokohama Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung Tel: 886-7-213-7828 Fax: 886-7-330-9305

Taiwan - Taipei Tel: 886-2-2508-8600 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels Tel: 43-7242-2244-39 Fax: 43-7242-2244-393 Denmark - Copenhagen Tel: 45-4450-2828

Fax: 45-4485-2829 France - Paris Tel: 33-1-69-53-63-20

Fax: 33-1-69-30-90-79 Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

10/26/12